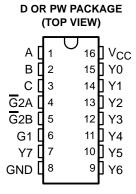
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- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of –55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- EPIC™ (Enhanced-Performance Implanted CMOS) Process
- Inputs Are TTL-Voltage Compatible
- Designed Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- † Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Incorporates Three Enable Inputs to Simplify Cascading and/or Data Reception
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)



## description/ordering information

The SN74AHCT138 3-line to 8-line decoder/demultiplexer is designed to be used in high-performance memory-decoding and data-routing applications that require very short propagation-delay times. In high-performance memory systems, this decoder can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of this decoder and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The conditions at the binary-select inputs and the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

#### ORDERING INFORMATION

TA	PACK	AGE <sup>‡</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
55°C to 125°C	SOIC - D	Tape and reel	SN74AHCT138MDREP	AHCT138MEP	
–55°C to 125°C	TSSOP - PW	Tape and reel	SN74AHCT138MPWREP	AT138EP	

<sup>&</sup>lt;sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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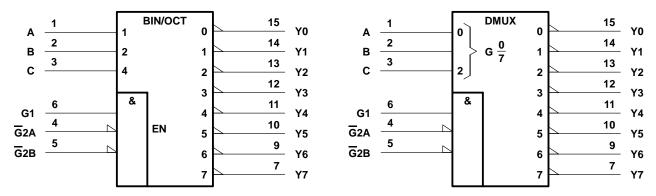


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#### **FUNCTION TABLE**

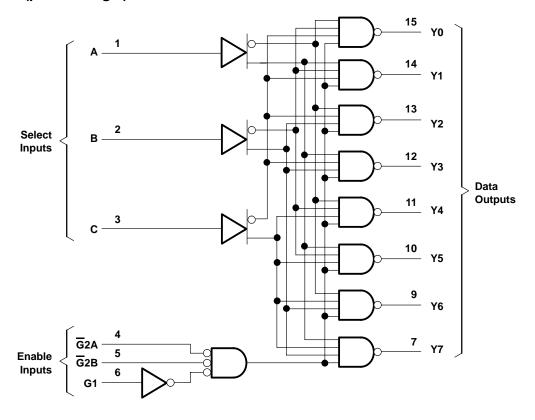
ENA	BLE INF	BLE INPUTS SELECT INPUTS			OUTPUTS								
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Х	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	X	Н	Х	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н
L	X	X	Х	Χ	X	Н	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н
Н	L	L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
Н	L	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
Н	L	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
Н	L	L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
Н	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н
Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L

# logic symbols (alternatives)†



<sup>&</sup>lt;sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (see Note 1)	
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	
Continuous current through V <sub>CC</sub> or GND	±75 mA
Package thermal impedance, $\hat{\theta}_{JA}$ (see Note 2): D package	73°C/W
PW package	108°C/W
Storage temperature range, T <sub>Stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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## recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
٧ <sub>I</sub>	Input voltage	0	5.5	V
٧o	Output voltage	0	VCC	V
Іон	High-level output current		-8	mA
loL	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	<b>–</b> 55	125	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Voc	T,	չ = 25°C	;	MIN	MAX	UNIT	
PARAMETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	IVIIIV	IVIAA	UNIT	
Vari	I <sub>OH</sub> = -50 μA		4.4	4.5		4.4		V	
VOH	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		٧	
V	I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1	V	
V <sub>OL</sub>	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.5	] '	
lį	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40	μΑ	
Δl <sub>CC</sub> †	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	mA	
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		2	10			pF	

<sup>†</sup> This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

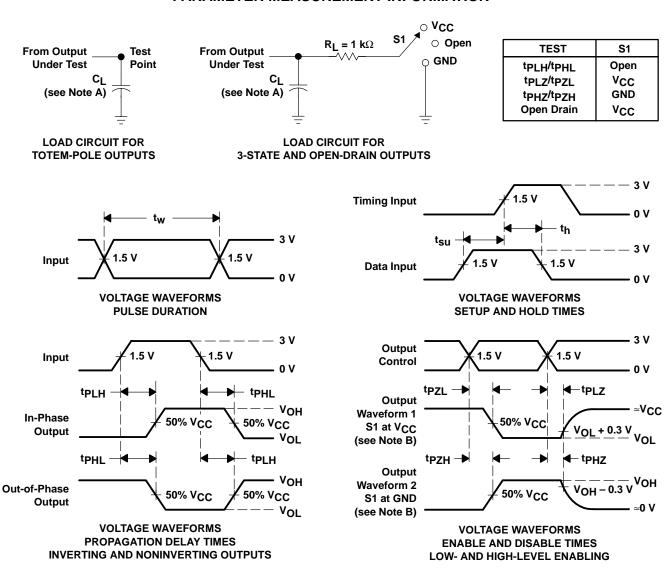
PARAMETER	FROM	то	LOAD	T,	չ = 25°C	;	MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIV	IVIAA	ONIT
tPLH	A, B, C	Any Y	C <sub>I</sub> = 15 pF		7.6	10.4	1	12	ns
<sup>t</sup> PHL	А, Б, С	Arry 1	C[ = 15 pr		7.6	10.4	1	12	115
<sup>t</sup> PLH	G1	Any Y	C <sub>I</sub> = 15 pF		6.6	9.1	1	10.5	20
<sup>t</sup> PHL	9	Ally 1	CL = 13 pr		6.6	9.1	1	10.5	ns
<sup>t</sup> PLH	<u></u>	Any Y	C <sub>L</sub> = 15 pF		7	9.6	1	11	ns
<sup>t</sup> PHL	GZA, GZB	Ally 1	оц = 10 рі		7	9.6	1	11	
<sup>t</sup> PLH	A, B, C	Any Y	C: -50 pE		8.1	11.4	1	13	ns
<sup>t</sup> PHL	А, Б, С	Ally f	$C_L = 50 \text{ pF}$		8.1	11.4	1	13	
<sup>t</sup> PLH	G1	Any V	C: -50 pE		7.1	10.1	1	11.5	ns
<sup>t</sup> PHL	9	Any Y	$C_L = 50 \text{ pF}$		7.1	10.1	1	11.5	1115
<sup>t</sup> PLH	$\overline{G}2A,\overline{G}2B$	Any Y	C <sub>L</sub> = 50 pF		7.5	10.6	1	12	ns
<sup>t</sup> PHL	GZA, GZB	Ally f	CL = 50 pr		7.5	10.6	1	12	115



## operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	14	pF

#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq$  3 ns,  $t_f \leq$  3 ns.
  - D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



#### **APPLICATION INFORMATION**

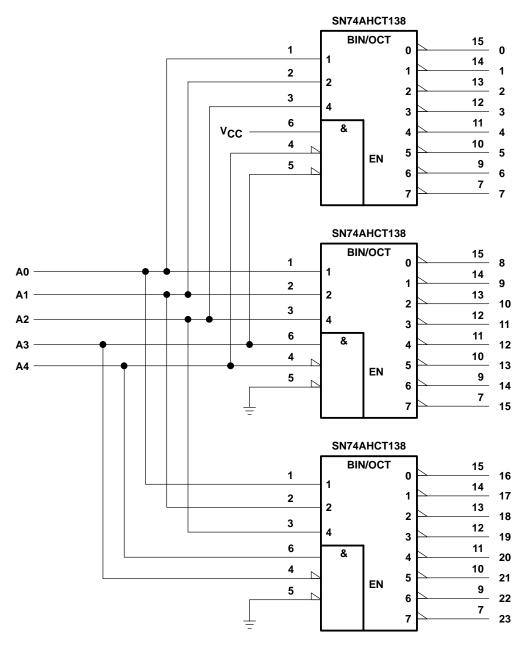


Figure 2. 24-Bit Decoding Scheme



#### **APPLICATION INFORMATION**

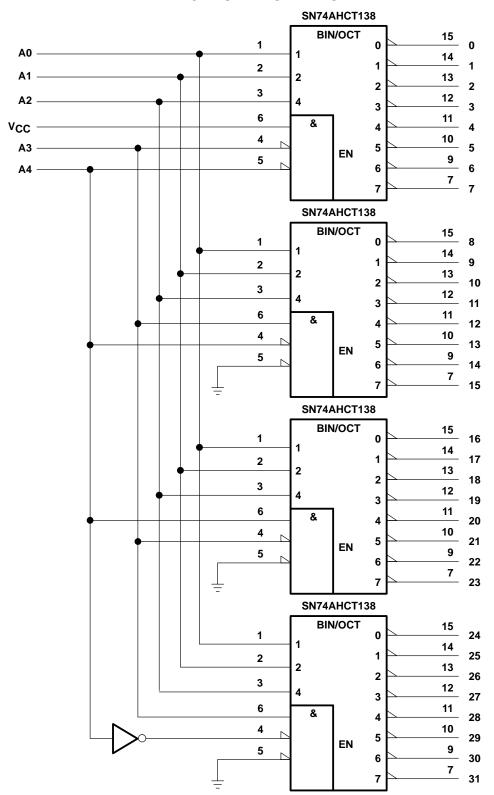


Figure 3. 32-Bit Decoding Scheme



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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
	('')	(2)			(0)	(4)	(5)		(0)
SN74AHCT138MDREP	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT138MEP
SN74AHCT138MDREP.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT138MEP
SN74AHCT138MPWREP	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AT138EP
SN74AHCT138MPWREP.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AT138EP
V62/03655-01XE	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AT138EP
V62/03655-01YE	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT138MEP

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF SN74AHCT138-EP:

■ Catalog : SN74AHCT138

• Military : SN54AHCT138

NOTE: Qualified Version Definitions:

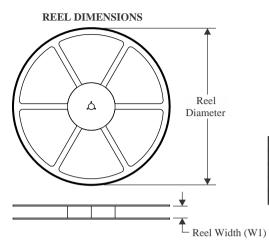
• Catalog - TI's standard catalog product

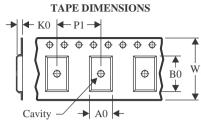
• Military - QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT138MDREP	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHCT138MPWREP	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT138MDREP	SOIC	D	16	2500	340.5	336.1	32.0
SN74AHCT138MPWREP	TSSOP	PW	16	2000	353.0	353.0	32.0

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